



#9B
BCC
2-10-03

SN 09/945,397

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gurtej Singh Sandhu et al.

Examiner: Judith A. Cothorn

Serial No.: 09/945,397

Group Art Unit: 2822

Filed: August 30, 2001

Docket: 303.541US2

Title: CONDUCTIVE CONTAINER STRUCTURES HAVING A DIELECTRIC CAP

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

In response to the Office Action mailed on October 7, 2002. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from January 7, 2003 to February 7, 2003.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect addition of new claims 117-121.

RECEIVED
FEB -5 2003
TECHNOLOGY CENTER 2800

117. (New) A method of forming a semiconductor structure, comprising the following processing steps in the order presented:
- forming an insulating layer on a substrate;
 - forming an opening in the insulating layer, wherein the opening has a bottom on an exposed portion of the substrate and sidewalls defined by the insulating layer;
 - forming a conductive layer on the insulating layer and the exposed portion of the substrate;
 - forming a fill layer on the conductive layer, wherein the fill layer fills the opening;
 - removing the conductive layer and the fill layer to a level below a top of the insulating layer, thereby forming a container structure having sidewalls comprised of the conductive layer on the sidewalls of the opening, and a closed bottom comprised of the conductive layer on the bottom of the opening;

09945397 190743 09945397
02/13/2003
01 FC:1202 72.00 CH
02 FC:1201 168.00 CH

Sub C1

B1

Rule 1.126